

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED


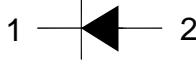

BA892WT-MS

Product specification

Applications

for band switching in VHF television tuners
and surface mount band switching circuits

Reference News

SOD-523	PIN Configuration	Marking
		

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

Absolute Maximum Ratings ($T_a = 25^{\circ}\text{C}$)

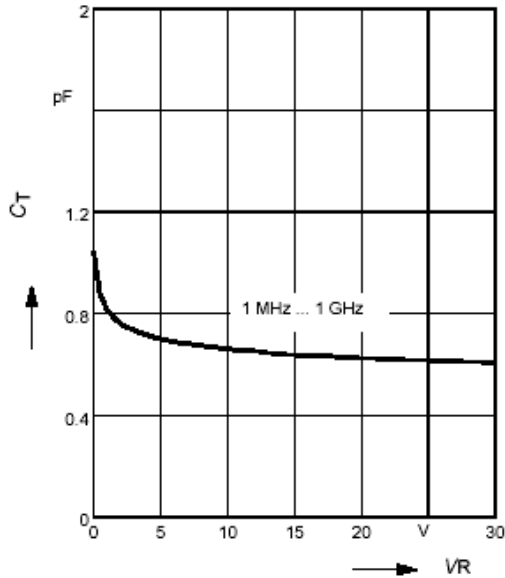
Parameter	Symbol	Value	Unit
Reverse Voltage	V_R	35	V
Forward Current	I_F	100	mA
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Operating Temperature Range	T_{op}	- 55 to + 125	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	- 55 to + 150	$^{\circ}\text{C}$

Characteristics at $T_a = 25^{\circ}\text{C}$

Parameter	Symbol	Min.	Typ.	Max.	Unit
Reverse Current at $V_R = 20\text{ V}$	I_R	-	-	20	nA
Forward Voltage at $I_F = 100\text{ mA}$	V_F	-	-	1	V
Diode Capacitance at $V_R = 1\text{ V}$, $f = 1\text{ MHz}$ at $V_R = 3\text{ V}$, $f = 1\text{ MHz}$ at $V_R = 0\text{ V}$, $f = 100\text{ MHz}$	C_T	0.65 0.6 -	- - 1	1.4 1.1 -	pF
Forward Resistance at $I_F = 3\text{ mA}$, $f = 100\text{ MHz}$ at $I_F = 10\text{ mA}$, $f = 100\text{ MHz}$	r_f	- -	- -	0.7 0.5	Ω
Series Inductance	L_s	-	0.6	-	nH

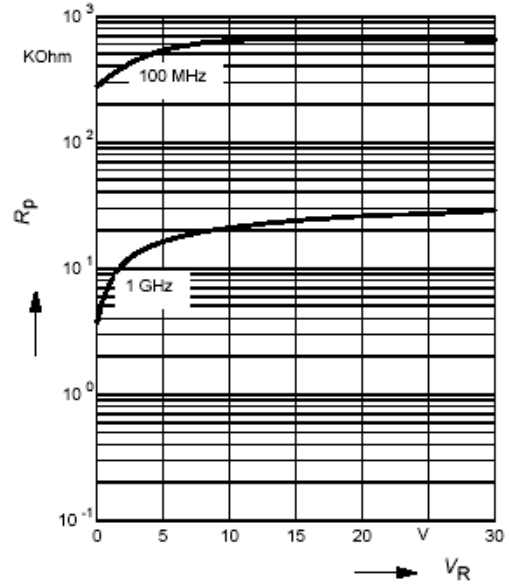
Diode capacitance $C_T = f(V_R)$

$f = \text{Parameter}$



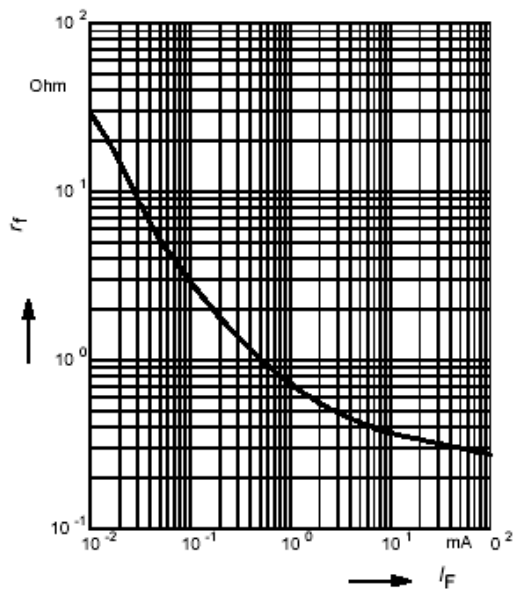
Reverse parallel resistance $R_P = f(V_R)$

$f = \text{Parameter}$



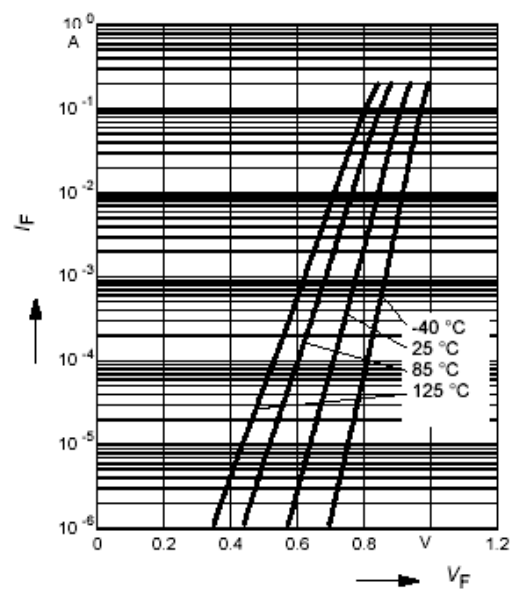
Forward resistance $r_f = f(I_F)$

$f = 100\text{MHz}$

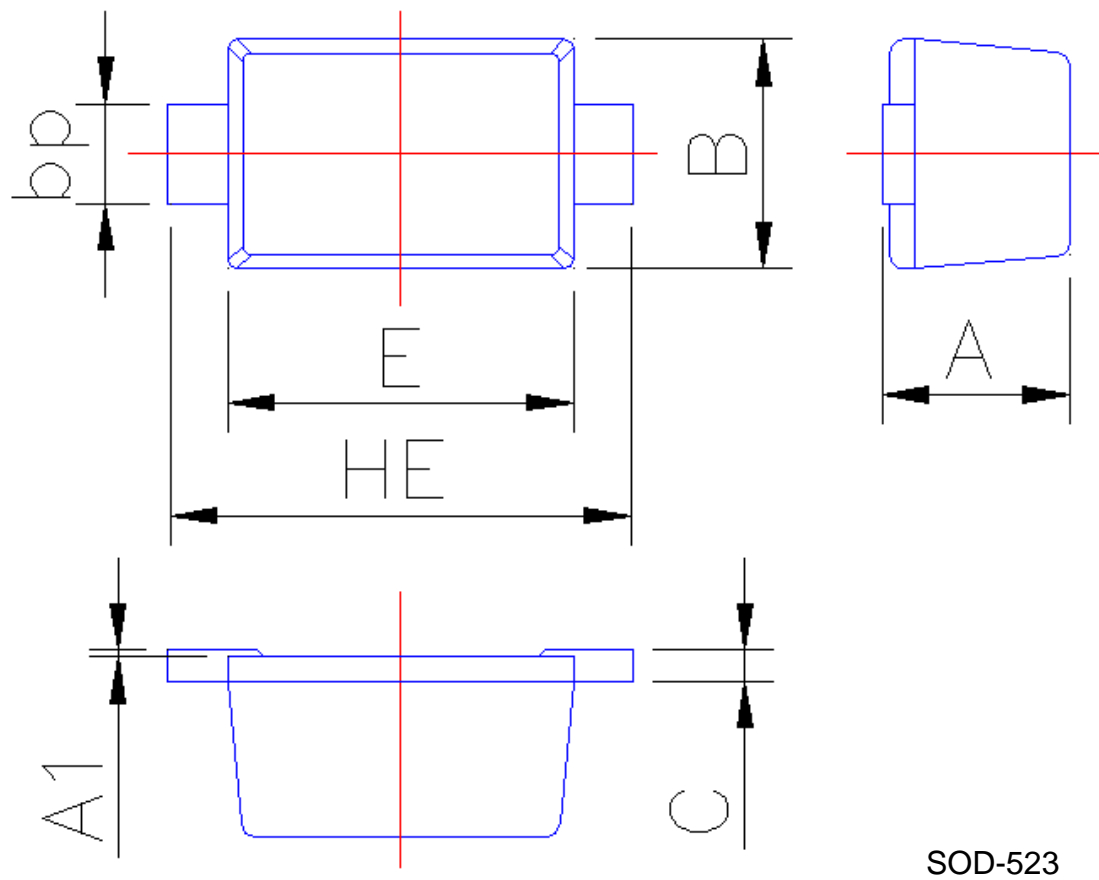


Forward current $I_F = f(V_F)$

$T_A = \text{Parameter}$



PACKAGE MECHANICAL DATA



Symbol	Dimension in Millimeters	
	Min	Max
A	0.60	0.75
A1	0	0.05
B	0.75	0.85
bp	0.25	0.40
C	0.09	0.15
E	1.15	1.25
HE	1.50	1.70

REELSPECIFICATION

P/N	PKG	QTY
BA892WT-MS	SOD-523	3000

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